| ITEM |  | ESC. | Q'TY | MATERIALS | TREATMENT |  | REMARK |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 1. |  | OVER | 1 | $\begin{aligned} & \text { THERMOPLASTIC } \\ & \text { PBT UL 94V-0 } \end{aligned}$ | MOLDED RED( OR BLUE , BLACK ) |  | - |
| 2. | ACT | UATOR | - | THERMOPLASTIC PBT UL 94V-0 | MOLDED WHITE |  | - |
| 3. | CO | NTACT | - | Be-BRONZE | GOLD PLATED |  | - |
| 4. | TER | RMINAL | - | PHOSPHOR BRONZE | GOLD PLATED |  | - |
| 5. |  | BASE | 1 | THERMOPLASTIC PBT UL $94 V-0$ | MOLDED BLACK |  | - |
| 6. |  | TAPE | 1 | BLENDED SILICONE AND RUBBER |  |  | - |
| (1) Prod. No. <br> Actuator Type: $\qquad$ = Short Key. <br> L = Long Key. |  |  |  |  |  | (Be) <br> Package = Tub <br> Soldering: V=Lead Free <br> Seal: = Regular T= Top Tape = Push D U <br> = Push D <br> Color Of Cov = Red <br> $B=$ Blue <br> $\mathrm{K}=$ Black | Style: <br> Sealed <br> wn "ON" <br> wn "OFF" |
| D |  |  |  | TITLE: <br> PIANO TYPE DIP SWITCHES <br> PRROD. NO. :DP.DPL-םחם---V |  |  |  |
| C |  |  |  |  |  | APPD. : |  |
| B |  |  |  |  |  | CHKD. |  |
| A | REL |  |  |  |  | PR. : |  |
| REV. | NO. | APPD. |  |  |  | REV : A SH | SHEET : 1 of 1 |




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| :---: | :---: | :---: | :---: |
| ［001•］ヶ¢ ${ }^{\text {c }}$ | ［19\％＇］79＊9 | Z | $\begin{aligned} & \text { ^ zo-Tda } \\ & \Omega \text { zo- d } \end{aligned}$ |
| ［00\％${ }^{\circ} \mathrm{B0}{ }^{\circ} \mathrm{s}$ | ［ $198 \cdot] 8 \mathrm{c} \cdot 6$ | $\varepsilon$ |  |
| ［008•］z9｀2 | ［19ヵ・］z々 11 | ■ |  |
| ［00ヵ・］91．01 | ［199•］9\％＇† | G |  |
| ［009•］02＇zi | ［199＇］08．91 | 9 | $\begin{aligned} & \hline \text { ^ 90-TdU } \\ & \text { И 90- d } \end{aligned}$ |
|  | ［ $192 \cdot] \ddagger 8 \cdot 61$ | 2 | $\begin{aligned} & \text { ^ LO-Td } \\ & \Omega \angle 0-\mathrm{da} \end{aligned}$ |
| ［002．］8L2I | ［198＊］88｀ 16 | 8 | $\begin{aligned} & \text { ^ 80-Td } \\ & \text { R 80- da } \end{aligned}$ |
| ［008•］z8．02 |  | 6 | $\begin{aligned} & \hline \text { ^ 60-Td } \\ & \text { ^60- da } \end{aligned}$ |
| ［006•］98＇zz | ［190｀${ }^{\circ}$ ］96．9z | 0I |  |
|  | ［19\％＇I］ $00 \cdot z \varepsilon$ | ZI |  |

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 －SGHONI NI GYV


## DP(L) SPECIFICATION

## 1.Style:

This specification describes "DUAL IN-LINE PACKAGE SWITCHES" mainly used as signal switch of electric devices with the general requirements of mechanical and electrical characteristics.
1.1 Operating Temperature Range : $-20^{\circ} \mathrm{C} \sim+70^{\circ} \mathrm{C}$
1.2 Storage Temperature Range : $-40^{\circ} \mathrm{C} \sim+85^{\circ} \mathrm{C}$
2. Current Range:
2.1 Non-Switching: 100mA, 50V DC
2.2 Switching : 25mA , 24V DC
3. Type of Actuation: Actuated by sliding
4. Test Sequence :


| DP(L) SPECIFICATION |  |  |  |  | $\begin{gathered} \hline \text { FILE No. } \\ \text { REV. } \\ \text { Page } \\ \hline \end{gathered}$ | $\begin{gathered} \text { E-B-AD03 } \\ 2 \quad D \\ 2 \quad 1 \\ \hline \end{gathered}$ |  |
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|  | 7 | Stop Strength | A static load of 1 kgf is applied in the operating direction and pulling direction operated for a period of 15 seconds. |  | There shall be no sign of damage mechanically |  |  |
|  |  | Soldering Heat Resistance | 1.Soldering Temperature : |  | As shown in item 2~6 |  |  |
|  |  |  | TEMP | TIME |  |  |  |
|  |  |  | $260^{\circ} \mathrm{C} \pm 5^{\circ} \mathrm{C}$ | $5 \pm 1 \mathrm{sec}$. |  |  |  |
|  | 8 |  | 2.Duration of Solder Immersion: $5 \pm 1$ sec. <br> 3.Frequency of Soldering Process: 2 times max. (PCB is 1.6 mm in thickness.) |  |  |  |  |
|  | 9 | Vibration | Shall be vibrated in accordance with Method 201A of MIL-STD-202F <br> (1)Frequency: $10-55-10 \mathrm{~Hz} 1 \mathrm{~min} / \mathrm{cycle}$. <br> (2) Direction: 3 vertical directions including the direction of operation. <br> (3) Test Time: 2 hours each direction. |  | As shown in item 2~6 |  |  |
|  | 10 | Shock | Shall be shocked in accordance with Method 213B condition A of <br> MIL-STD-202F <br> (1)Acceleration: 50G. <br> (2)Action Time : $11 \pm 1 \mathrm{~m} \mathrm{sec}$. <br> (3) Testing Direction: 6 sides. <br> (4) Test cycle : <br> 3 times in each direction |  | As shown in item 2~6 |  |  |
|  | 11 | Solderabilit y | (1)Soldering Temperature: $230 \pm 5^{\circ} \mathrm{C}$ <br> (2)Flux: 5-10 seconds. <br> (3) Duration of solder Immersion: <br> $3 \pm 0.5 \mathrm{sec}$. |  | No anti-soldering and the coverage of dipping into solder must more than $75 \%$ was requested. |  |  |
| $\stackrel{\rightharpoonup}{\text { ¢ }}$ | 12 | Operation Life | Measurements shall be made following the test set forth below: <br> (1)25 mA, 24V DC resistive load <br> (2)Rate of Operation: 15~20 cycles/ minute <br> (3)Cycle of Operation: 2000 cycles. |  | $\begin{array}{\|l} \text { (1)As sh } \\ \text { (2Conta } \\ 100 \mathrm{~m}! \\ \text { (final- } \end{array}$ | in ite esist ax. test) |  |


| DP(L) SPECIFICATION |  |  |  | FILE No REV. <br> Page | $\begin{gathered} \text { E-B-AD03 } \\ \text { D } \\ 3 \quad 1 \quad 3 \\ \hline \end{gathered}$ |  |
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|  | 13 | Resistance Low Temperature | Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : <br> (1)Temperature : $-40^{\circ} \mathrm{C} \pm 3^{\circ} \mathrm{C}$ <br> (2)Time: 96 hours | As shown in item 2~6 |  |  |
|  | 14 | Resistance High Temperature | Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : <br> (1)Temperature : $85^{\circ} \mathrm{C} \pm 2^{\circ} \mathrm{C}$ <br> (2)Time: 96 hours | 1.As shown in item 3~6 <br> 2.Contact Resistance: $100 \mathrm{~m} \Omega$ max. |  |  |
|  | 15 | Humidity Resistance | Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : <br> (1)Temperature: $40^{\circ} \mathrm{C} \pm 2^{\circ} \mathrm{C}$ <br> (2)Relative Humidity :90~95\% <br> (3)Time: 96 hours | 1 As shown in item 4,6 <br> 2 Contact Resistance: $100 \mathrm{~m} \Omega$ max. <br> 3 Insulation Resistance : $10 \mathrm{M} \Omega \mathrm{min}$. |  |  |

## 5. SOLDERING CONDITIONS:

■ Manual Soldering

| Soldering Temperature | Max. $350^{\circ} \mathrm{C}$ |
| :---: | :---: |
| Continuous Soldering Time | Max. 3 seconds |

- Precautions in Handling

1. Care should be exercised so that flux from the upper part of the printed circuit board does not adhere to the switch.
2. Don't clean the switch body except with top tape sealed type, which can only spray of cleaning method from top of $\mathrm{s} / \mathrm{w}$.
3. Please make sure that there is no flux rose over the surface of the PCB
